

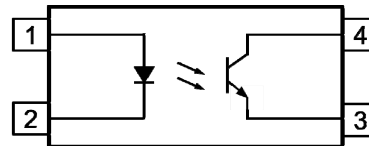
ISLT100xV



DESCRIPTION

The ISLT100xV series optocouplers consists of an infrared emitting diode optically coupled to an NPN silicon photo transistor.

These devices belong to Isocom Long Creepage Range of Optocouplers.



1 Anode
2 Cathode
3 Emitter
4 Collector

FEATURES

- Long Creepage 8mm
- High AC Isolation voltage 5000V_{RMS}
- CTR Selections Available
- Wide Operating Temperature Range -55°C to 110°C
- Pb Free and RoHS Compliant
- UL Approval E91231
- VDE Approval 40042752

APPLICATIONS

- Switching Mode Power Supply
- System Appliances
- Measuring Instruments
- Telecommunication Equipments
- Signal Transmission between Systems of Different Potentials and Impedances

ORDER INFORMATION

- Available in Tape and Reel with 3000pcs per reel

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Stresses exceeding the absolute maximum ratings can cause permanent damage to the device. Exposure to absolute maximum ratings for long periods of time can adversely affect reliability.

Input

Forward Current	60mA
Peak Forward Current (1μs, pulse)	1.5A
Reverse Voltage	6V
Power dissipation	100mW

Output

Collector to Emitter Voltage V _{CEO}	80V
Emitter to Collector Voltage V _{ECO}	7V
Collector Current	50mA
Power Dissipation	150mW

Total Package

Isolation Voltage	5000V _{RMS}
Total Power Dissipation	250mW
Operating Temperature	-55 to 110 °C
Storage Temperature	-55 to 125 °C
Lead Soldering Temperature (10s)	260°C

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ISLT100xV

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

INPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Forward Voltage	V_F	$I_F = 50\text{mA}$		1.45	1.5	V
Reverse Current	I_R	$V_R = 6\text{V}$			10	μA
Input Capacitance	C_{IN}	$V_F = 0\text{V}, f = 1\text{kHz}$		50		pF

OUTPUT

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Collector-Emitter Breakdown Voltage	BV_{CEO}	$I_C = 0.1\text{mA}, I_F = 0\text{mA}$	80			V
Emitter-Collector Breakdown Voltage	BV_{ECO}	$I_E = 0.1\text{mA}, I_F = 0\text{mA}$	7			V
Collector-Emitter Dark Current	I_{CEO}	$V_{CE} = 20\text{V}, I_F = 0\text{mA}$			100	nA



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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

COUPLED

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit			
Current Transfer Ratio	CTR	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$	ISLT1001V	50		600	%		
			ISLT1007V	80		160			
			ISLT1008V	130		260			
			ISLT1009V	200		400			
		$I_F = 10\text{mA}, V_{CE} = 5\text{V}$	ISLT1002V	63		125			
			ISLT1003V	100		200			
			ISLT1004V	160		320			
			$I_F = 1\text{mA}, V_{CE} = 5\text{V}$	ISLT1002V	22				
		ISLT1003V		34					
		ISLT1004V		56					
		Collector-Emitter Saturation Voltage		$V_{CE(sat)}$	$I_F = 10\text{mA}, I_C = 1\text{mA}$				0.3
		Floating Capacitance	C_f	$V_F = 0\text{V}, f = 1\text{MHz}$				1.0	pF
Turn On Time	t_{on}	$V_{CE} = 2\text{V}, I_C = 5\text{mA}, R_L = 100\Omega$		4		μs			
Turn Off Time	t_{off}			3		μs			
Output Rise Time	t_r				18	μs			
Output Fall Time	t_f				18	μs			

ISOLATION

Parameter	Symbol	Test Condition	Min	Typ.	Max	Unit
Isolation Voltage	V_{ISO}	R.H. = 40% to 60%, $t = 1\text{ min}$ (Note 1)	5000			V_{AC}
Input - Output Isolation Resistance	R_{I-O}	R.H. = 40% to 60% $V_{I-O} = 500\text{VDC}$ (Note 1)	5×10^{10}			Ω

Note 1 : Measured with input leads shorted together and output leads shorted together.

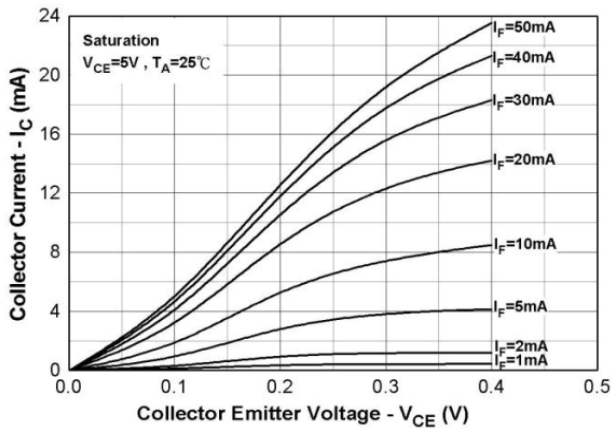


Fig 1 Collector Current vs Collector-Emitter Voltage (1)

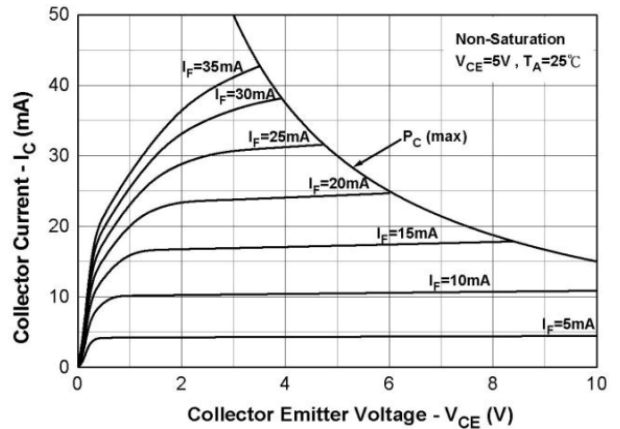


Fig 2 Collector Current vs Collector-Emitter Voltage (2)

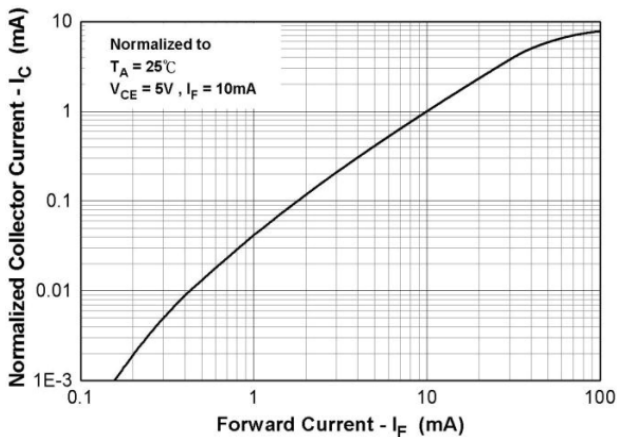


Fig 3 Normalized Collector Current vs Forward Current

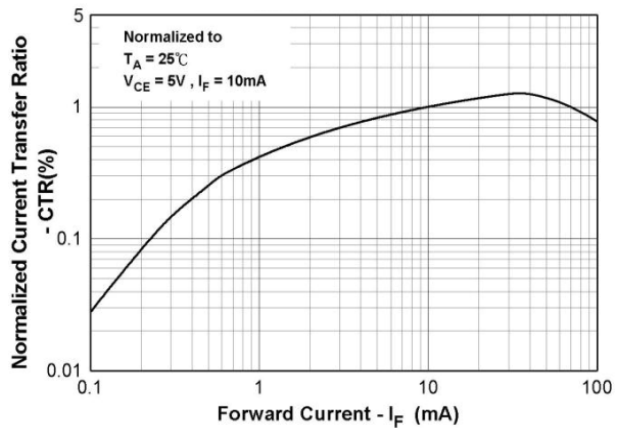


Fig 4 Normalized Current Transfer Ratio vs Forward Current

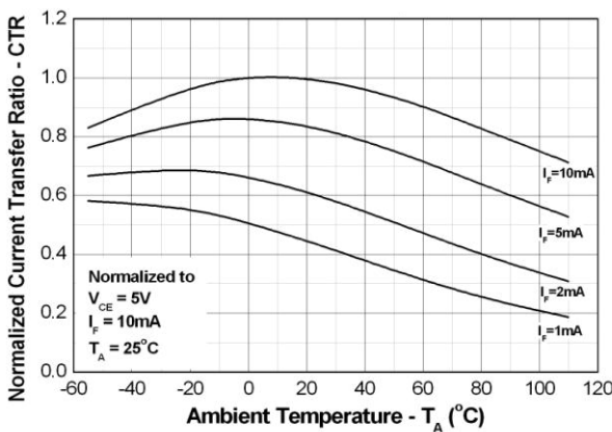


Fig 5 Normalized Current Transfer Ratio vs Ambient Temperature (1)

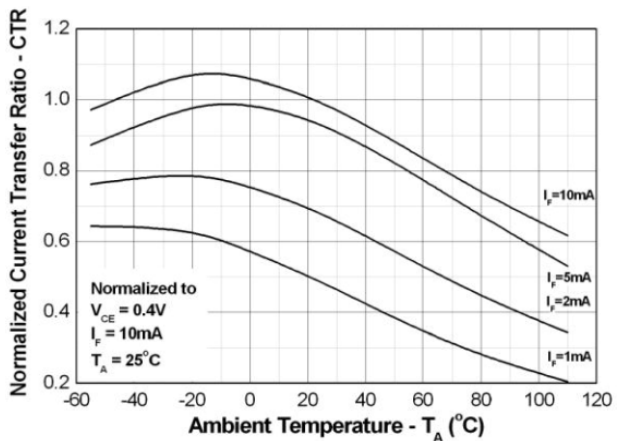


Fig 6 Normalized Current Transfer Ratio vs Ambient Temperature (2)

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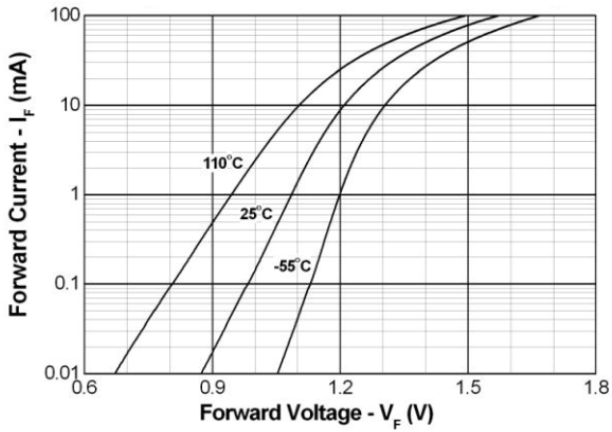


Fig 7 Forward Current vs Forward Voltage

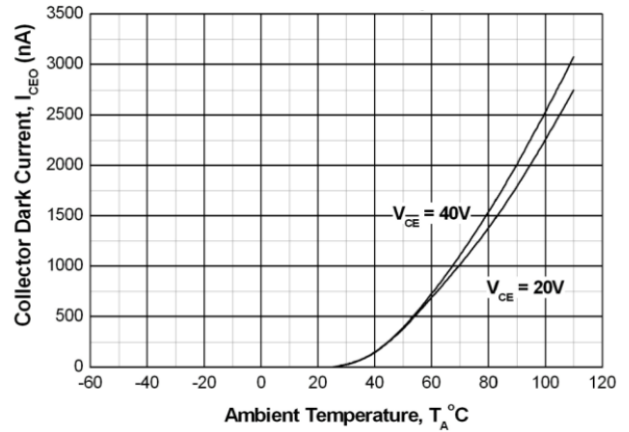


Fig 8 Collector Dark Current vs Ambient Temperature

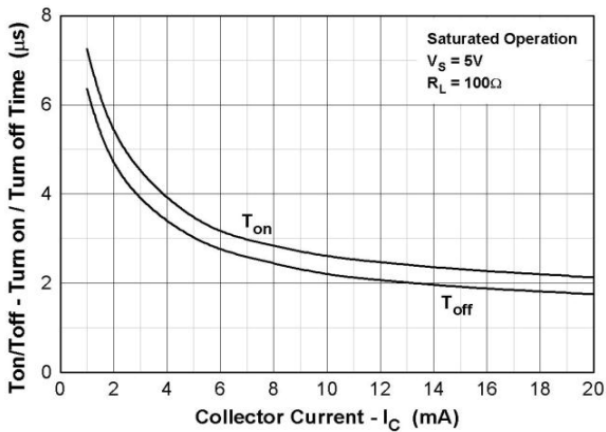


Fig 9 Turn on/off Time vs Collector Current

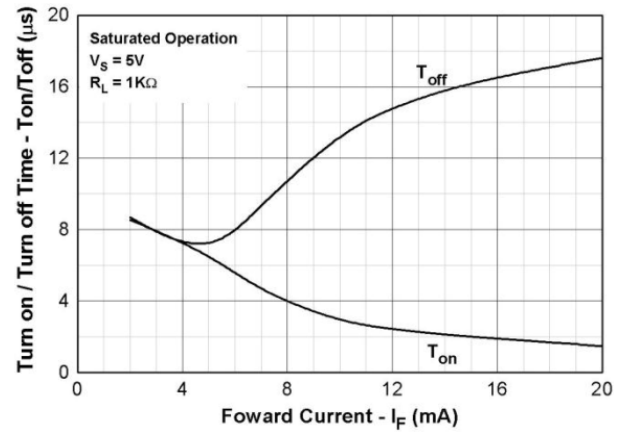
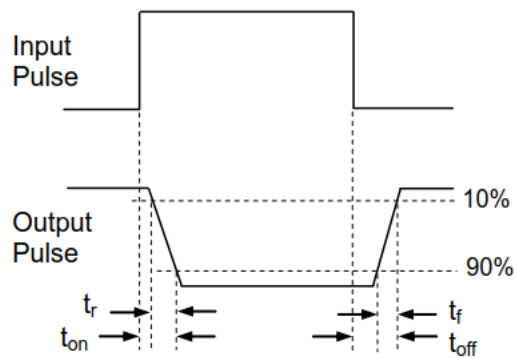
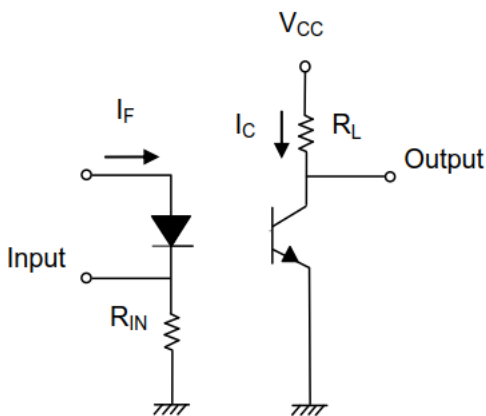


Fig 10 Turn on/off Time vs Forward Current



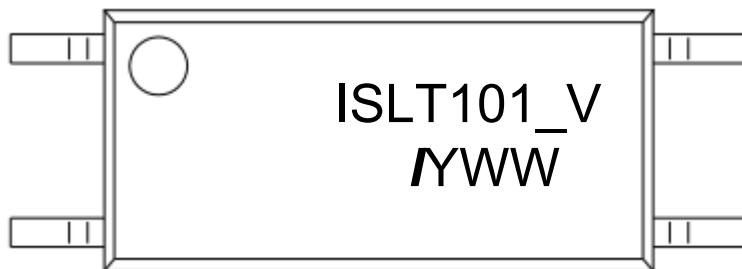
Switching Time Test Circuit and Waveforms

ISLT100xV

ORDER INFORMATION

ISLT100xV			
After PN	PN	Description	Packing quantity
Any CTR Grade	ISLT1001V, ISLT1002V, ISLT1003V, ISLT1004V, ISLT1007V, ISLT1008V, ISLT1009V	Surface Mount Tape & Reel	3000 pcs per reel

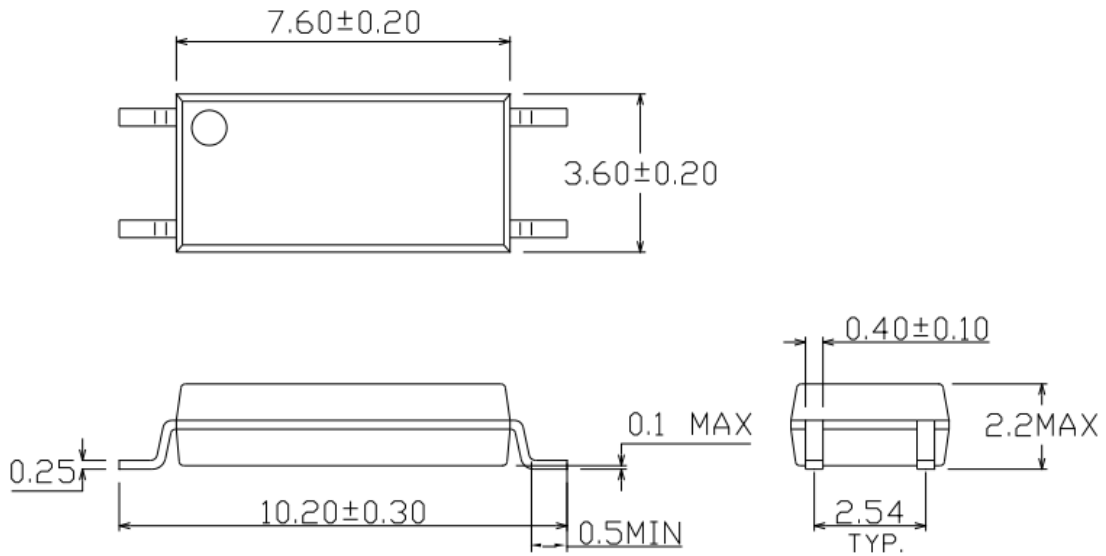
DEVICE MARKING



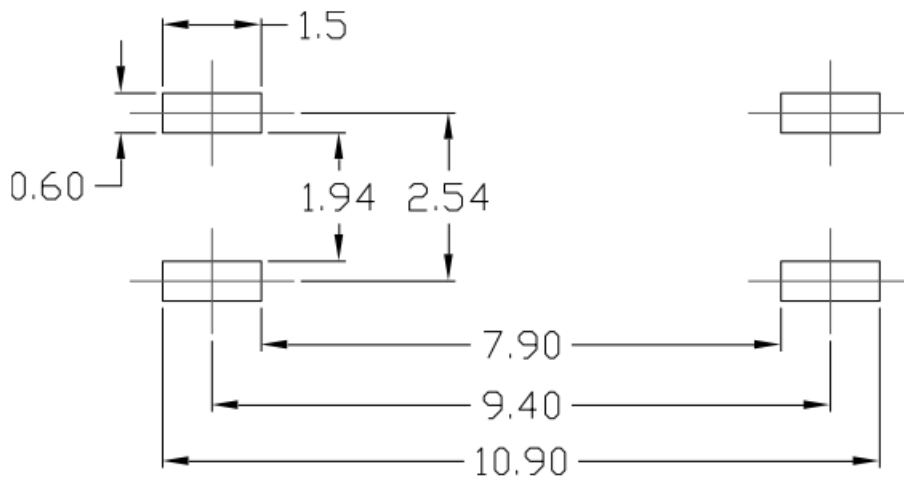
ISLT101_V denotes Device Part Number where “_” denotes the CTR Grade
 I denotes Isocom
 Y denotes 1 digit Year code
 WW denotes 2 digit Week code

ISLT100xV

PACKAGE DIMENSIONS (mm)

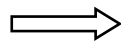
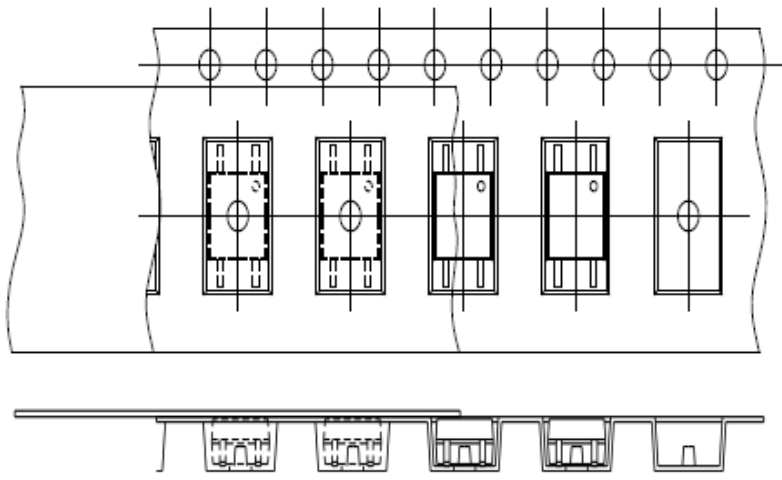


RECOMMENDED SOLDER PAD LAYOUT (mm)

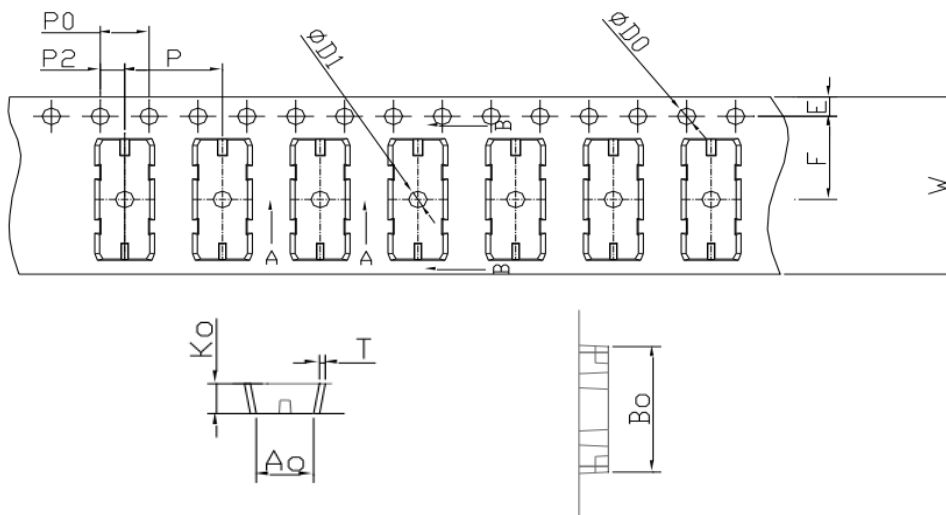


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TAPE AND REEL PACKAGING



Direction of feed from reel

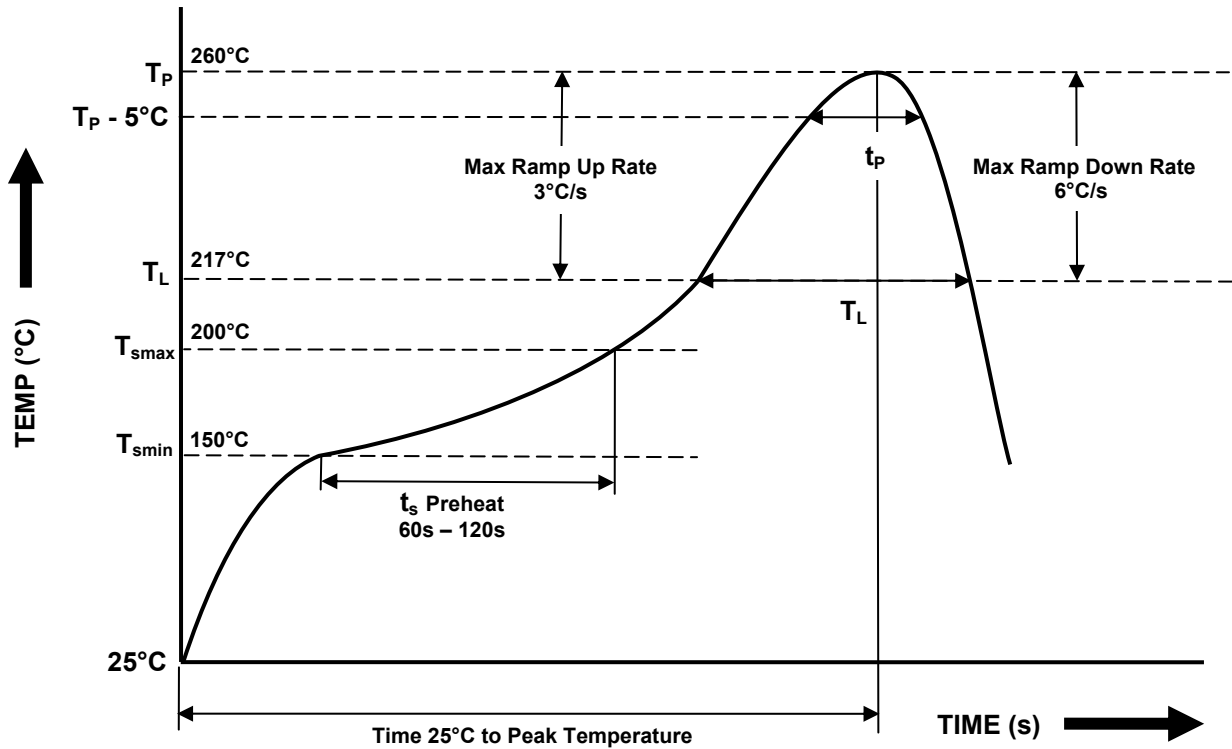


Dimension No.	A₀	B₀	D₀	D₁	E	F
Dimension (mm)	3.9±0.10	10.82±0.10	1.5+0.1/-0	1.5±0.10	1.75±0.10	7.5±0.10
Dimension No.	P₀	P	P₂	T	W	K₀
Dimension (mm)	4.0±0.15	8.0±0.10	2.0±0.10	0.4±0.05	16.0±0.3	2.25±0.1

IR REFLOW SOLDERING TEMPERATURE PROFILE

One Time Reflow Soldering is Recommended.

Do not immerse device body in solder paste.



Profile Details	Conditions
Preheat	
- Min Temperature (T _{SMIN})	150°C
- Max Temperature (T _{SMAX})	200°C
- Time T _{SMIN} to T _{SMAX} (t _s)	60s - 120s
Soldering Zone	
- Peak Temperature (T _P)	260°C
- Liquidous Temperature (T _L)	217°C
- Time within 5°C of Actual Peak Temperature (T _P - 5°C)	30s
- Time maintained above T _L (t _L)	60s - 100s
- Ramp Up Rate (T _L to T _P)	3°C/s max
- Ramp Down Rate (T _P to T _L)	6°C/s max
Average Ramp Up Rate (T _{smax} to T _P)	3°C/s max
Time 25°C to Peak Temperature	8 minutes max



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